ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of

Printed Circuit Board with Isolated Metallic Substrate Comprising an Integrated Cooling System

Application Number:

Confirmation Number: First Named Applicant:

Carles Borrego Bel

Attorney Docket Number:

8134ES

Art Unit:

Examiner: Search string:

(6226178 or 5875097 or 6219246 or 6212071 or 6190941 or 6032355 or 6201300

or 6201701).pn

<u>Certification:</u> This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:

That each item of information contained in the information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6226178	2001-05-01	Border et al	B1	361	687
	2	5875097	1999-02-23	Amaro et al	Α	361	704
	3	6219246	2001-04-17	Edevold et al	B1	361	707
	4	6212071	2001-04-03	Roessler et al	B1	361	704
	5	6190941	2001-02-20	Heinz et al	B1	438	106
	6	6032355	2000-03-07	Tseng et al	Α	29	840
	7	6201300	2001-03-13	Tseng et al	B1	257	706
	8	6201701	2001-03-13	Linden et al	B1	361	720

Signature

Examiner Name	Date